

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of KIM et al.	METHOD FOR FORMING ISOLATION
Serial No.: 10/001,314) LAYER OF SEMICONDUCTOR DEVICE)
Filed: November 14, 2001	Attorney Docket: TJK/204
	Group Art Unit: 2823
	Examiner: N. Berezny
)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, 4114 on 2003.

Douglas S. Rupert

Attorney for Applicants

Reg. No. 44,434

4114 Date of Signature:

Assistant Commissioner for Patents

Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

This paper is filed in response to the Office Action mailed January 14, 2003 in connection with the above-designated application.

TECHNOLOGY CEHTER 2800



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE:

APPLICANTS:

Kim et al.

EXAMINER:

N. Berezny

SERIAL NO.:

10/001,314

GROUP:

2823

FILED:

11/14/2001

CASE NO.:

TJK/204

TITLE:

METHOD FOR FORMING ISOLATION LAYER OF

SEMICONDUCTOR DEVICE

AMENDMENT TRANSMITTAL LETTER

Box Non-Fee Amendment Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

Please find enclosed the following documents pertaining to the above referenced application:

- 1. Response to Office Action (3 pages)
- 2. Return Receipt Postcard

There is no fee due for the filing of this amendment. In the event of non-payment or improper payment of a required fee, the Commissioner is hereby authorized to charge or credit additional fees to **Deposit Account No. 23-2126**. A duplicate copy of this letter is enclosed for fee purposes.

Respectfully submitted,

Douglas S. Rupert Registration No. 44,434 **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231, on April 14, 2003.

Signature

Date